

			* * · · · · · · · · · · · · · · · · · ·	•	•	
As a below named inventor,	I hereby declare	that:			·.	
My residence, post office an	d citizenship are	as stated below n	ext to my name,		* 1	
I believe I am the original, fi plural names are listed below type Washing Machin [X] is attached hereto	v) of the subject e. the specificat	matter claimed an	d for which a patent	is sought on the i	ivention entitled]	
	amended on		(if a	milicable)		
specification, including the	I hereby state claims, as amend	that I have rev led by any amendr	iewed and understanent referred to above	and the contents	of the above i	dentified
in accordance with Title 37, (I acknowledge Code of Federal l	the duty to disclose Regulations, Section	information which in 1.56(a).	known to me to	be material to par	entability
application(s) for patent or country other than the Unit application for patent or in application on which priority	inventor's certified States of Am ventor's certifica	cate, or 365(a) of erica listed below	and have also identif	al application whi ied below, by che	ich designated at ecking the box, an	least one
Prior Foreign Applic <u>Number</u>	eation(s):	<u>C</u>	ountry		eign Filing Date outh/Day/Year	
	•					
				 		
I hereby claim the benefit un	der 35 U.S.C. 11		States provisional app	lication(s) listed b	elow.	
Application Number(s):	<u>.</u>		Filing Date (M	lonth/Day/Yea	<u>D</u>	* *
	e e				•	
I hereby claim the benefit un designating the United States not disclosed in the prior Un 112. I acknowledge the duty available between the filing d	s of America, list ated States or PC to disclose info	ed below and, inso T international apportunity of the second seco	far as the subject mat dication in the manne material to patentabil	ter of each of the exprovided by the ity as defined in	claims of this app first panigraph of 37 CFR 156 which	lication is 35 U.S.C. h became
Prior U. S. Applic or PCT Parent Nu		Filing Date (M	onth/Bay/Year)		Patent Numbe applicable)	<u>r</u>
				e de la companya de La companya de la co		
						
· · · · · · · · · · · · · · · · · · ·				that all contains	mada on inform	aring and
I hereby declare that all state belief are believed to be true like so made are punishable	and further tha	t these statements	were made with the k	nowledge that wil	lful false statemen	ts and the

such willful false statements may jeopardize the validity of the application or any patent issued thereon.

I hereby appoint the following attorney(s) and/or agent(s):Daniel Y.J. Kim, Registration No. 36,186 and Mark L. Fleshner, Registration No. 34,596; Carl R. Wesolowski, Registration No. 40,372, John C. Eisenhart, Registration No. 38,128, Carol L. Druzbick, Registration No. 40,287; Anthony H. Nourse, Registration No. 46,121; Laura L. Lee, Registration No. 48,752; Rene A. Vazquez, Registration No. 38,647; Donald R. McPhail, Registration No. 35,811; Timothy M. Speer, Registration No. 47,355; Samuel W. Ntiros, Registration No. 39,318; Mark R. Buscher, Registration No. 35,006; and Daniel H. Sherr, Registration No. 46,425, all of

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